Silicon P Channel MOS FET High Speed Power Switching

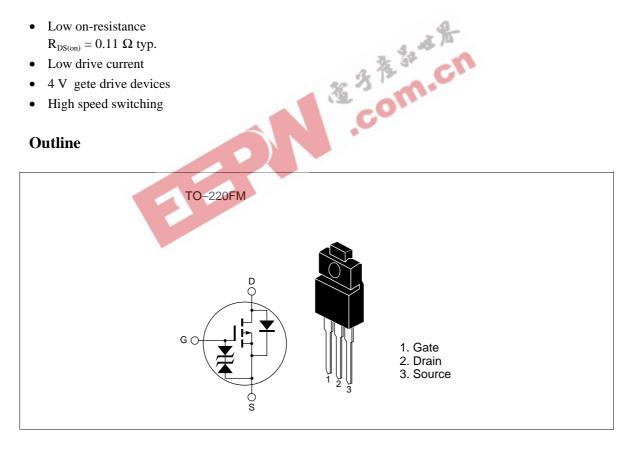
HITACHI

ADE-208-579B (Z) 4th. Edition Jun 1998

Features

- Low on-resistance $R_{\text{DS(on)}} = 0.11~\Omega$ typ.
- Low drive current
- 4 V gete drive devices
- High speed switching

Outline





Absolute Maximum Ratings $(Ta = 25^{\circ}C)$

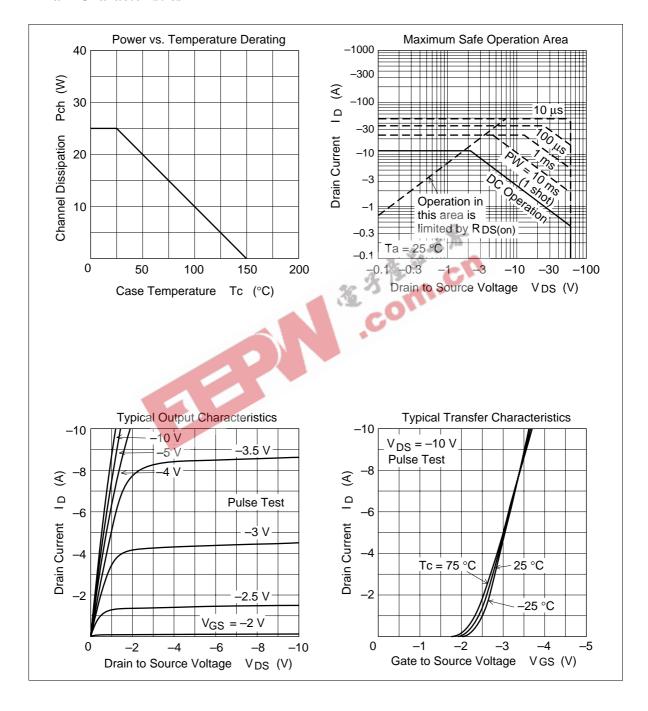
Item	Symbol	Ratings	Unit			
Drain to source voltage	V _{DSS}	-60	V			
Gate to source voltage	$V_{\sf GSS}$	±20	V			
Drain current	I _D	-12	A			
Drain peak current	Note1 D(pulse)	-48	A			
Body-drain diode reverse drain current	I _{DR}	-12	A			
Avalenche current	I _{AP} Note3	-12	A			
Avalenche energy	E _{AR} Note3	12	mJ			
Channel dissipation	Pch ^{Note2}	25	W			
Channel temperature	Tch	150	°C			
Storage temperature	Tstg	-55 to +150	°C			
Note: 1. PW ≤ 10μs, duty cycle ≤ 1 %						
2. Value at Tc = 25°C						
Note: 1. $PW \le 10\mu s$, duty cycle ≤ 1 % 2. Value at $Tc = 25^{\circ}C$ 3. Value at $Tch = 25^{\circ}C$, $Rg \ge 50 \Omega$						
Electrical Characteristics ($Ta = 25$ °C)						
ltem Sy	mbol Min Typ	Max Unit Tes	t Conditions			

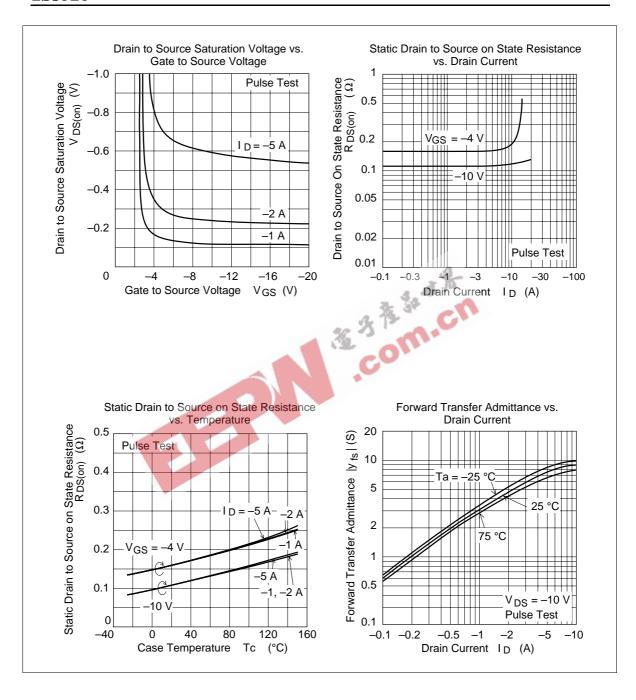
Electrical Characteristics (Ta = 25° C)

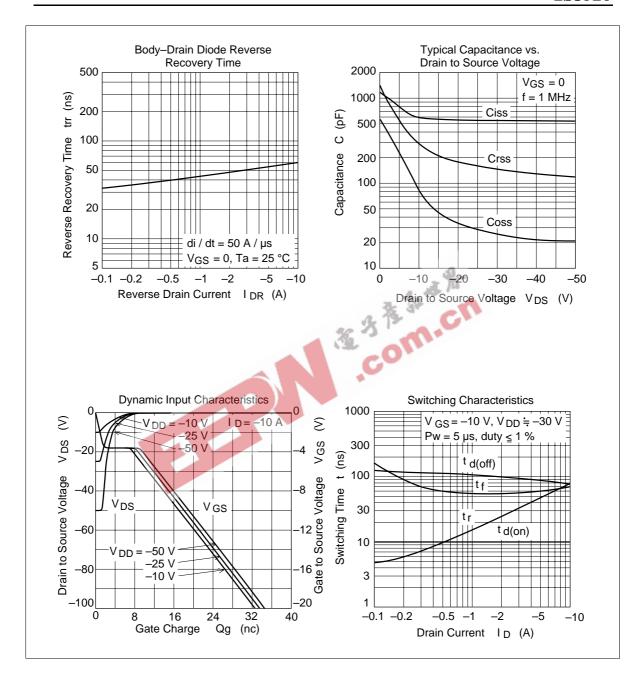
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	V _{(BR)DSS}	-60	_	_	V	$I_{D} = -10 \text{mA}, VGS = 0$
Gate to source breakdown voltage	V _{(BR)GSS}	±20	_	_	V	$I_{G} = \pm 100 \mu A, V_{DS} = 0$
Zero gate voltege drain current	I _{DSS}	_	_	-10	μΑ	$V_{DS} = -60 \text{ V}, V_{GS} = 0$
Gate to source leak current	I _{GSS}	_	_	±10	μΑ	$V_{GS} = \pm 16V, V_{DS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	-1.0	_	-2.0	V	$I_{D} = -1 \text{mA}, V_{DS} = -10 \text{V}$
Static drain to source on state	R _{DS(on)}	_	0.11	0.15	Ω	$I_D = -6A, V_{GS} = -10V^{Note4}$
resistance	R _{DS(on)}	_	0.16	0.23	Ω	$I_{\rm D} = -6A, V_{\rm GS} = -4V^{\rm Note4}$
Forward transfer admittance	y _{fs}	5	8	_	S	$I_D = -6A, V_{DS} = -10V^{Note4}$
Input capacitance	Ciss	_	580	_	pF	V _{DS} = -10V
Output capacitance	Coss	_	300	_	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	_	85	_	pF	f = 1MHz
Turn-on delay time	t _{d(on)}	_	10	_	ns	$V_{GS} = -10V, I_{D} = -6A$
Rise time	t _r	_	55	_	ns	$R_L = 6\Omega$
Turn-off delay time	t _{d(off)}	_	85	_	ns	_
Fall time	t _f	_	60	_	ns	_
Body-drain diode forward voltage	V_{DF}	_	-1.2	_	V	$I_F = -12A, V_{GS} = 0$
Body–drain diode reverse recovery time	t _{rr}	_	60		ns	$I_F = -12A, V_{GS} = 0$ diF/ dt = 50A/ μ s
Note: 4 Dules test			•	•	•	

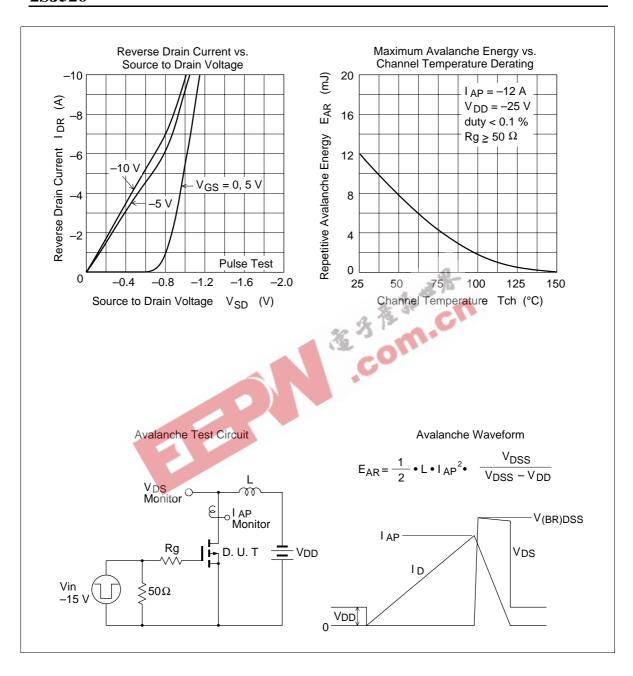
Note: 4. Pulse test

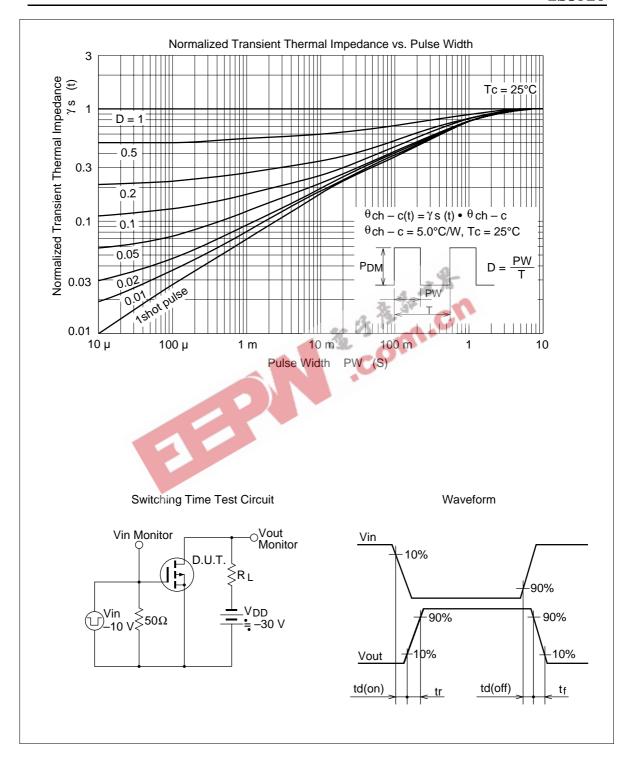
Main Characteristics





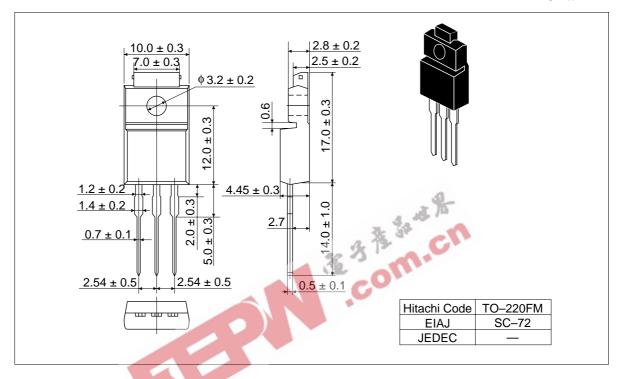






Package Dimensions

Unit: mm



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